

L Number	Hits	Search Text	DB	Time stamp
1	2178641	semiconductor ic chip die (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:42
2	77317	(bond bonding) with (wire wiring wires)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:43
3	110867	(bumps balls flipchip (flip adj chip)) and (semiconductor ic chip die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:43
4	382328	heat with (sink spreader radiate metal slug lid cover top)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:44
5	3457	(semiconductor ic chip die (integrated adj circuit)) and ((bond bonding) with (wire wiring wires)) and ((bumps balls flipchip (flip adj chip)) and (semiconductor ic chip die (integrated adj circuit))) and (heat with (sink spreader radiate metal slug lid cover top))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:48
6	382908	(Silicon polysilicon glass) with (substrate carrier board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:50
7	2664	((semiconductor ic chip die (integrated adj circuit)) and ((bond bonding) with (wire wiring wires)) and ((bumps balls flipchip (flip adj chip)) and (semiconductor ic chip die (integrated adj circuit))) and (heat with (sink spreader radiate metal slug lid cover top))) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:50
8	1253	((Silicon polysilicon glass) with (substrate carrier board)) and (((semiconductor ic chip die (integrated adj circuit)) and ((bond bonding) with (wire wiring wires)) and ((bumps balls flipchip (flip adj chip)) and (semiconductor ic chip die (integrated adj circuit))) and (heat with (sink spreader radiate metal slug lid cover top))) and package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/02 11:51